

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of)
)
Takayama et al.)
)
Serial No.: 09/598,736)
)
Filed: June 21, 2000)
)
For: Wiring Material, Semiconductor Device)
Provided With A Wiring Using The Wiring)
Material And Method Of Manufacturing)
Thereof)
)
Art Unit: 2811)
)
Confirmation No.: 5820)
)
Examiner: Hung K. Vu)

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

RESPONSE H (AFTER FINAL)

Sir:

Applicants have the following response to the Final Rejection of October 10, 2006.

Applicants appreciate the Examiner's allowance of Claims 28-39.

Applicants will now address the Examiner's remaining rejections in the order in which they appear in the Final Rejection.

Claim Rejections - 35 USC §102

In the Final Rejection, the Examiner rejects Claims 1, 5 and 115 under 35 USC §102(b) as being anticipated by Oikawa et al. (US 4,770,948). This rejection is respectfully traversed.